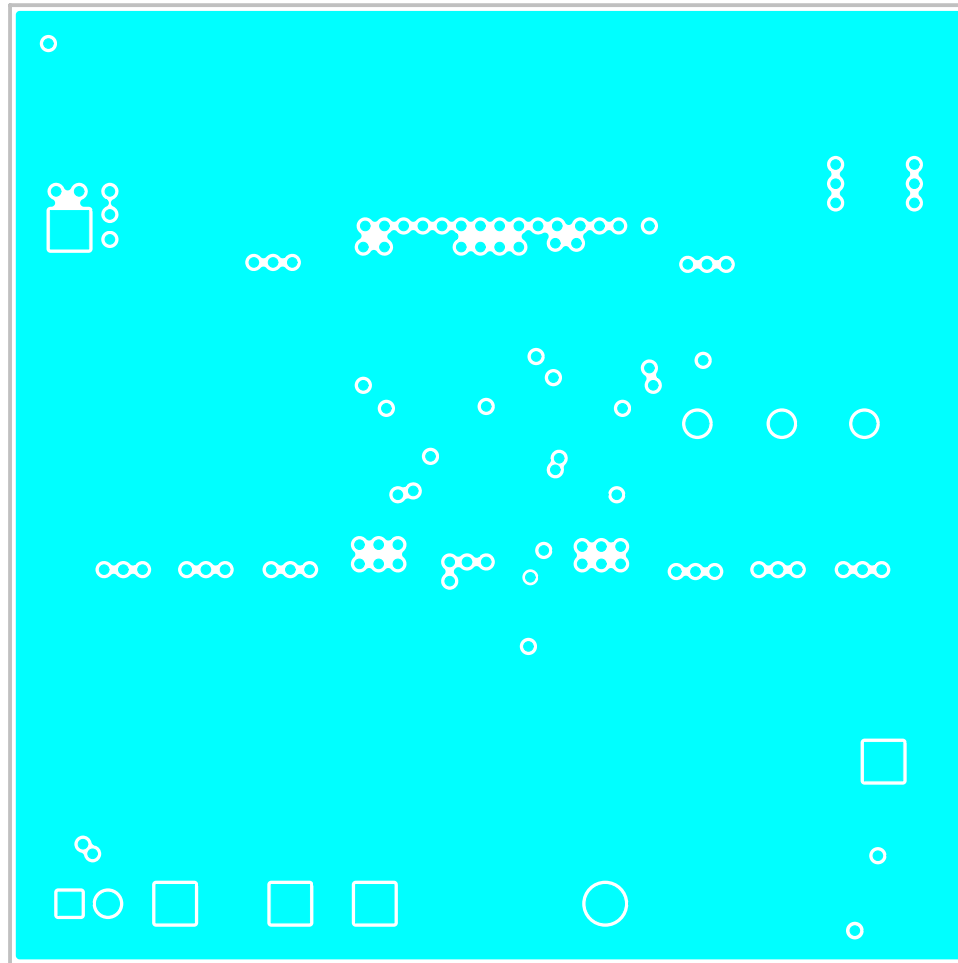
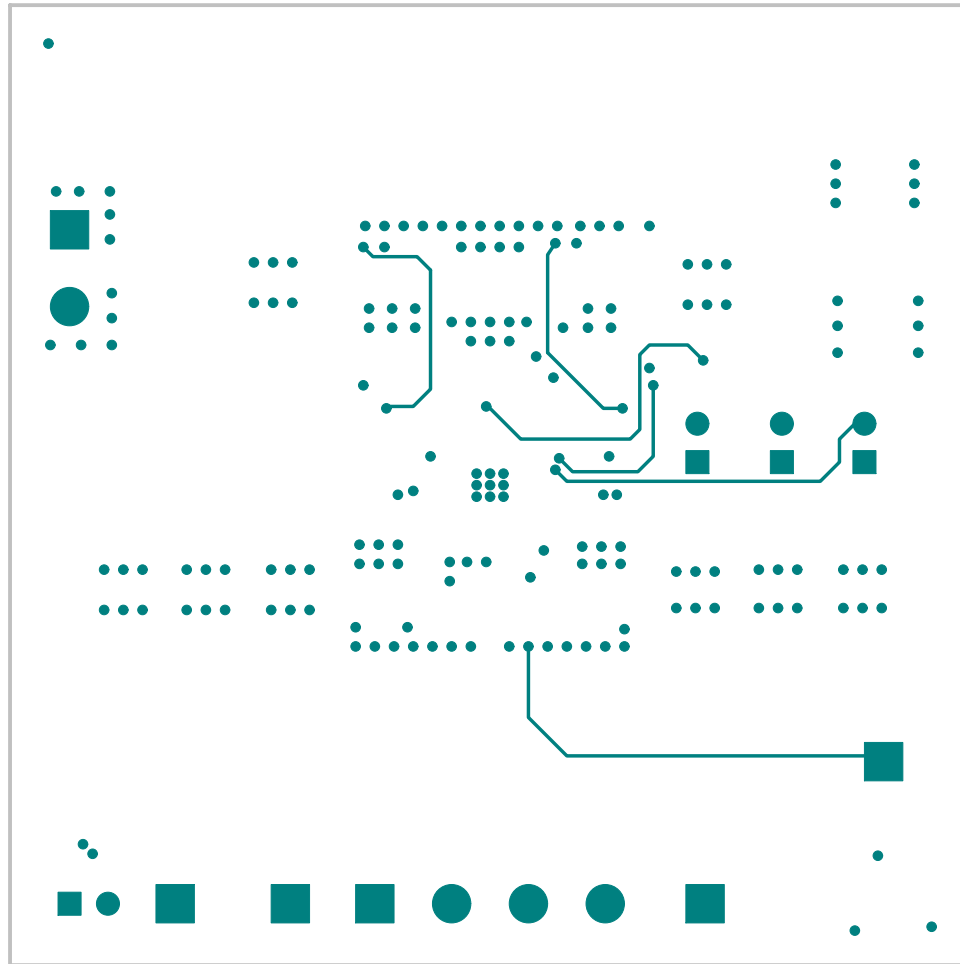


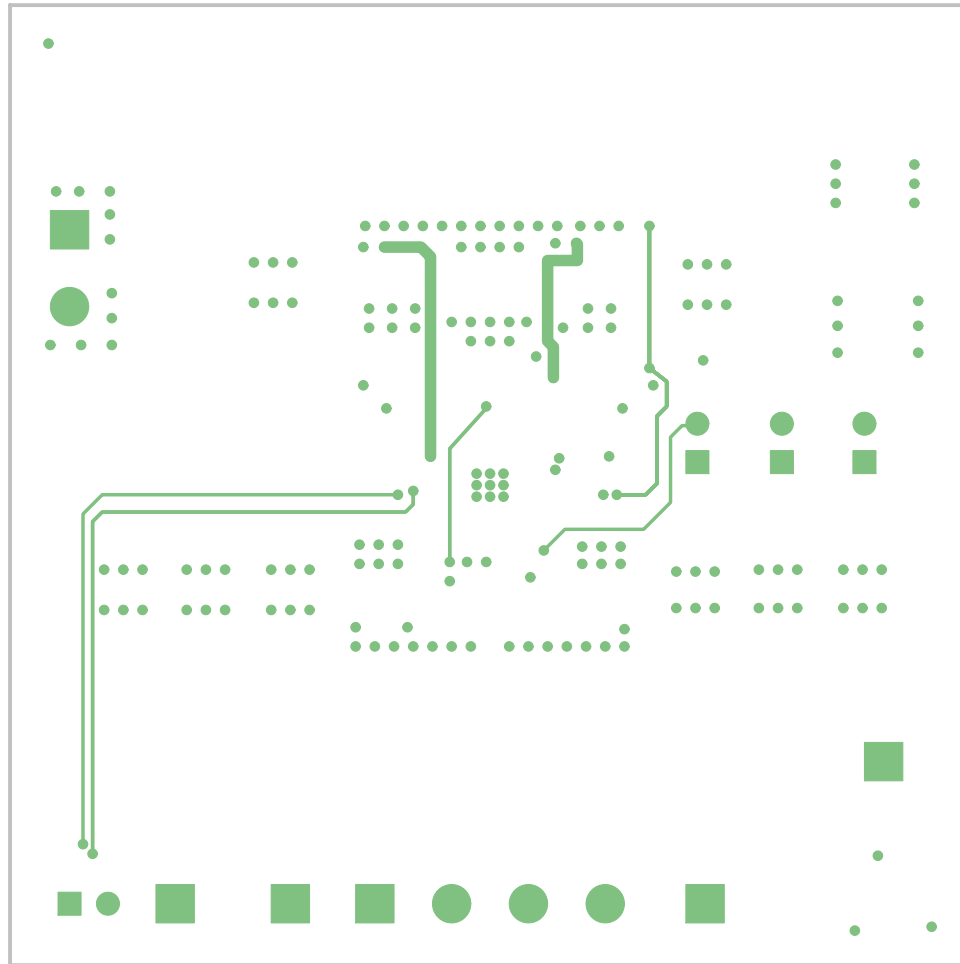
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	
Board No. PMP6552	Rev. A	L1										
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou		Modified Date: 1/10/2011				Time Stamp: 09:08:41			



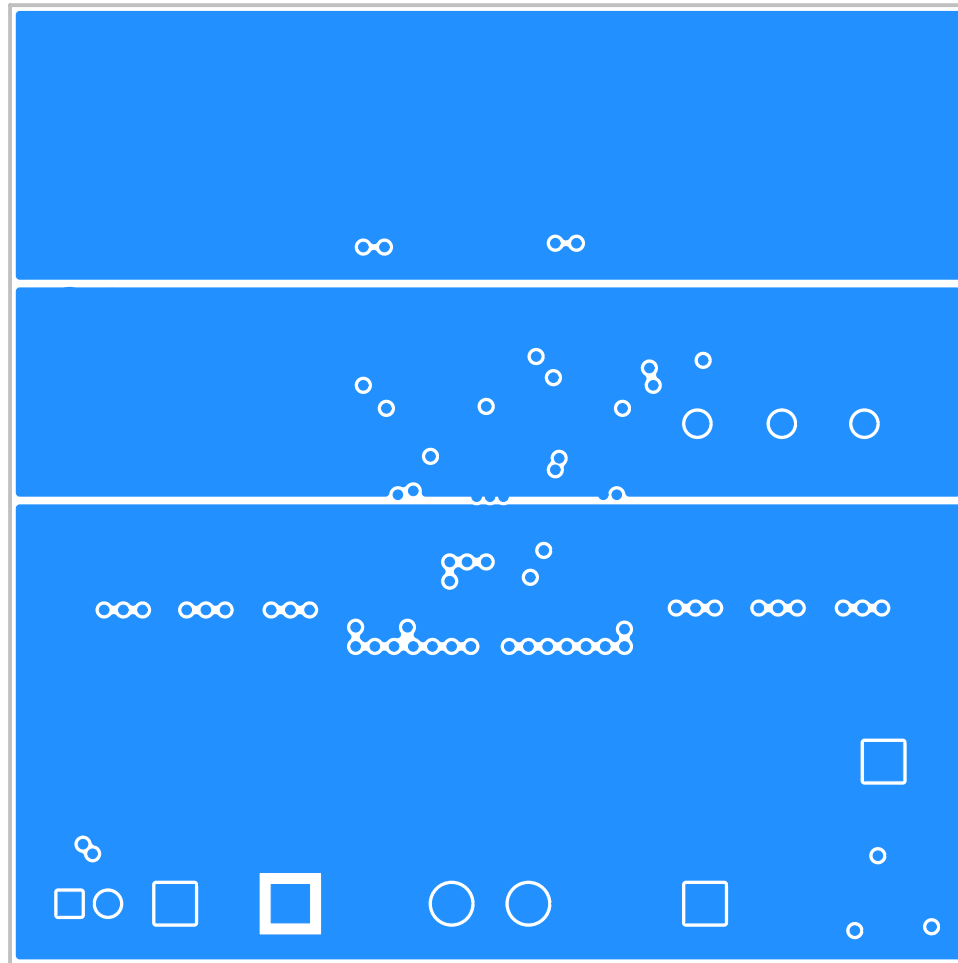
TEXAS INSTRUMENTS		Copper Layer Name					Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6552	Rev. A		L2										
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou		Modified Date: 1/10/2011				Time Stamp: 09:08:41				



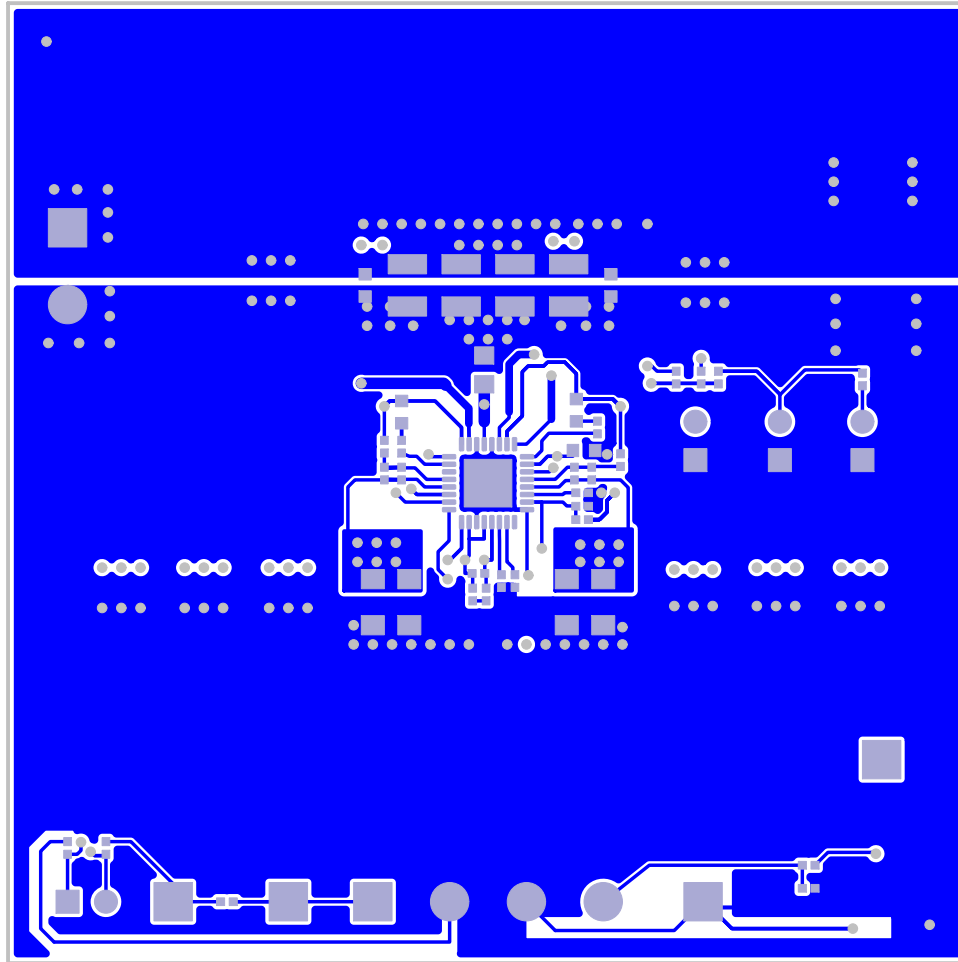
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	PMP6552	Rev.	A			L3						
Date:	1/10/2011	Filename:	Engineer:	T Zhou	PCB Dsgnr:	T Zhou	Modified Date:	1/10/2011		Time Stamp:	09:08:41	



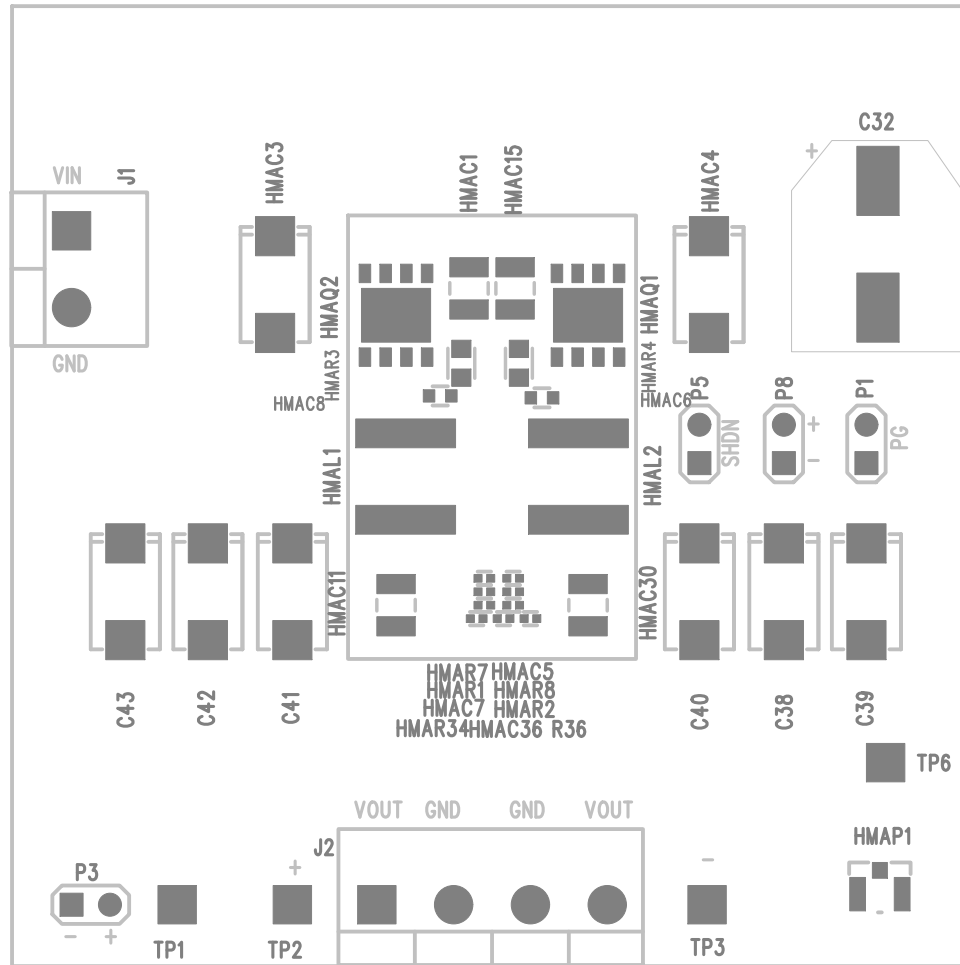
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6552	Rev. A			L4								
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou	Modified Date: 1/10/2011	Time Stamp: 09:08:41							



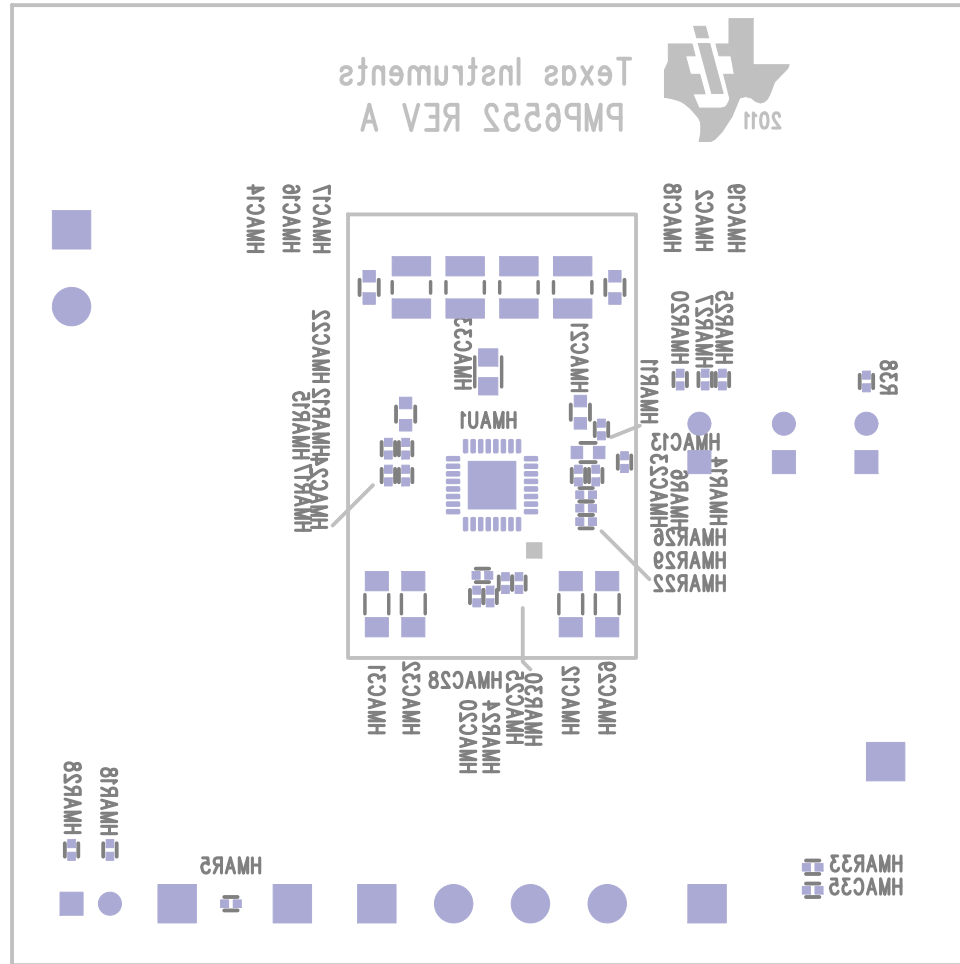
TEXAS INSTRUMENTS			Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
			Top	Internal			Bot	Top	Bot	Top	Bot	Top	
Board No. PMP6552	Rev. A				L5								
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou		Modified Date: 1/10/2011				Time Stamp: 09:08:41				



TEXAS INSTRUMENTS		Copper Layer Name					Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6552	Rev. A					L6							
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou		Modified Date: 1/10/2011				Time Stamp: 09:08:41				



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	
Board No.	Rev.						S1					
PMP6552	A											
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou	Modified Date: 1/10/2011					Time Stamp: 09:08:41			

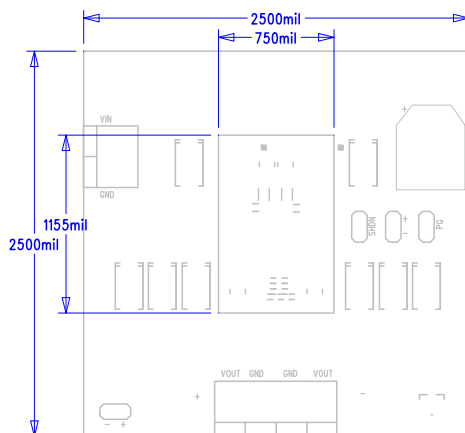


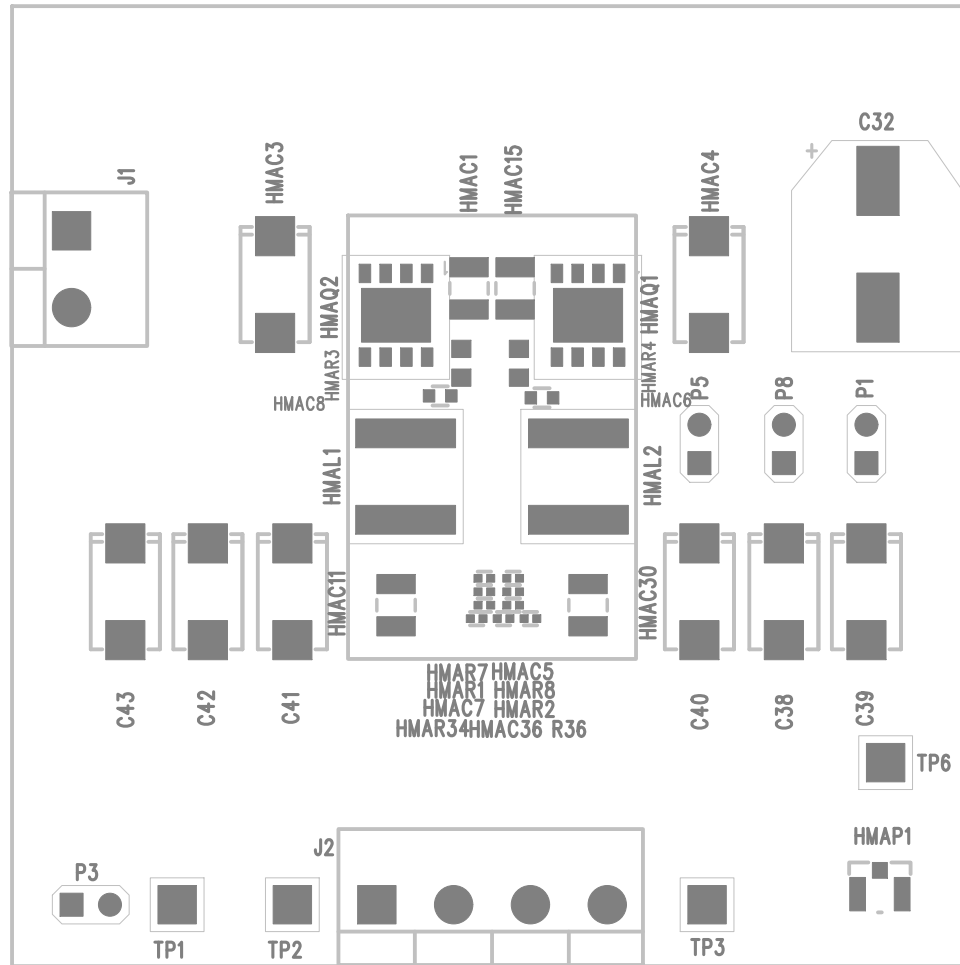
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal			Bot	Top	Bot	Top	Bot	Top	
Board No. PMP6552	Rev. A						S6					
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou	Modified Date: 1/10/2011				Time Stamp: 09:08:41				

FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
<input type="checkbox"/> 0.031 <input checked="" type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____	<input checked="" type="checkbox"/> 1 OZ. <input type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT	
<input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX	<input type="checkbox"/> 0.010/0.010 <input type="checkbox"/> 0.008/0.007 <input checked="" type="checkbox"/> 0.009/0.006	<input type="checkbox"/> SINGLE SIDED <input type="checkbox"/> 4 LAYER <input type="checkbox"/> 8 LAYER <input type="checkbox"/> _____	<input type="checkbox"/> 2 LAYER <input checked="" type="checkbox"/> 6 LAYER <input type="checkbox"/> 10 LAYER	

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:** ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
- BASE LAMINATE:** PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
- SOLDERMASK:** SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
- PLATING:** HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
- FINISH:** PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
- LEGEND:** IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
- MARKINGS:** BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
- WORKMANSHIP:** PCB BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
- DOCUMENTATION:** PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
- DRILL SIZES:** HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
- PANEL BORDER:** ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
- PROCESS CHANGES:** NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



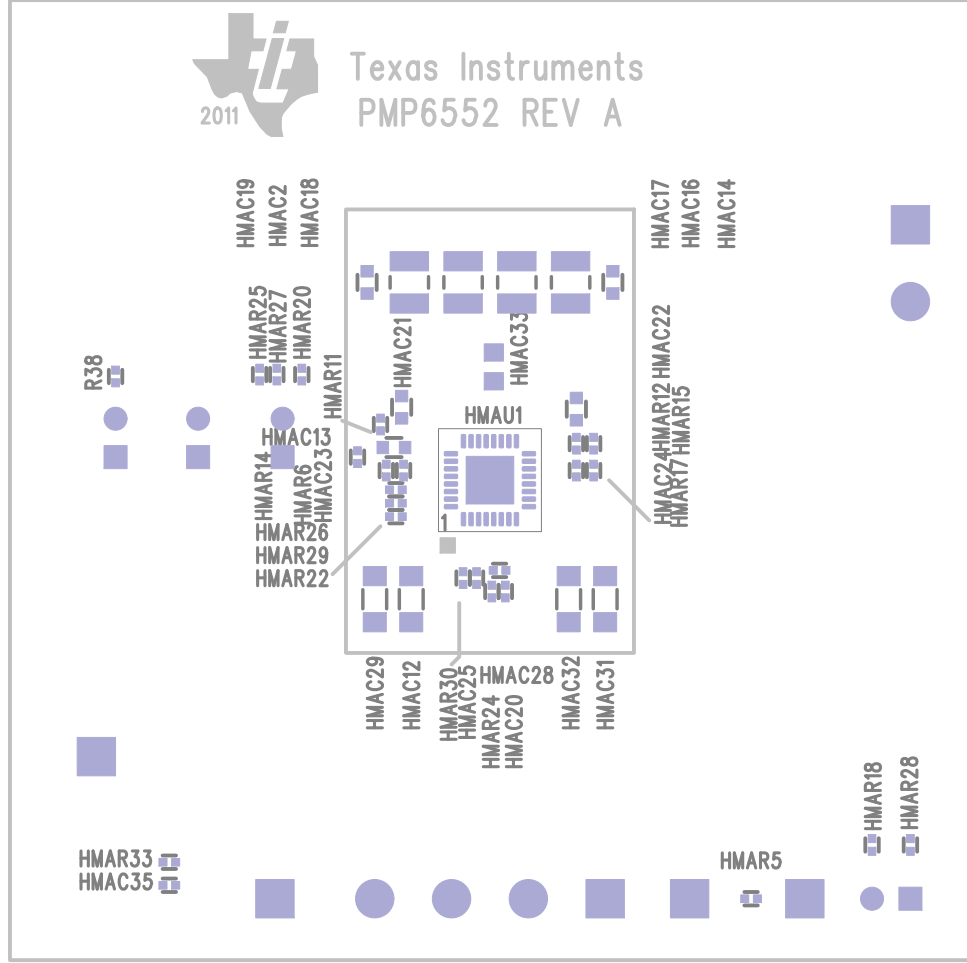


TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP6552	Rev. A									TA		
Date: 1/10/2011	Filename:	Engineer: T Zhou	PCB Dsgnr: T Zhou	Modified Date: 1/10/2011					Time Stamp: 09:08:41			



Texas Instruments
PMP6552 REV A

2011



Date: 1/10/2011		Filename:		Engineer: T Zhou		PCB Design: T Zhou		Modified Date: 1/10/2011		Time Stamp: 09:08:41	
Board No. PMP6552		Rev. A		Top		Internal		Bot			
				Copper Layer Name		Silkscreen		Mask		Assembly	
										Bot	
										Top	
										Bot	

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